

<b>INFORMATION DISCLOSURE CITATION IN AN APPLICATION</b>		ATTY. DOCKET NO. <b>67161-134</b>		SERIAL NO.			
<b>(PTO-1449)</b>		APPLICANT <b>Koyu ASAI, et al.</b>					
		FILING DATE <b>December 03, 2003</b>		GROUP			
<b>U.S. PATENT DOCUMENTS</b>							
EXAMINER'S INITIALS	CITE NO.	Document Number Number-Kind Code <sup>2</sup> (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear		
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<b>FOREIGN PATENT DOCUMENTS</b>							
EXAMINER'S INITIALS	CITE NO.	Foreign Patent Document Country Codes - Number - Kind Codes (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines Where Relevant Figures Appear	Translation	
						Yes	No
WA		JP 7-108323	04/21/1995	NEC CORP	(Japan w/English Abstract)		
WA		JP 9-213800	08/15/1997	NEC CORP	(Japan w/English Abstract)		
WA		JP 8-264847	10/11/1996	FUJITSU LTD	(Japan w/English Abstract)		
<b>OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)</b>							
EXAMINER'S INITIALS	CITE NO.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.					
WA		"Stress-Induced Voiding Under Vias Connected to Wide Cu Metal Leads", E.T. Ogawa et al., 2002 IEEE International Reliability Physics Symposium Proceedings, April 7-11, 2002.					
WA		"Mechanisms of Stress-Induced Voids in Multi-Level Cu Interconnects", Byung-Lyul Park et al., IEEE 2002 International Interconnect Technology Conference, June 3-5, 2002.					
WA		"Thermal Stress of 140nm-width Cu damascene interconnects", Norio Okada et al., IEEE 2002 International Interconnect Technology Conference, June 3-5, 2002.					
		EXAMINER				DATE CONSIDERED	

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